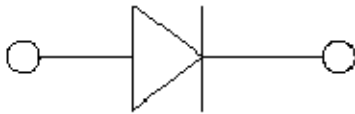


Small Signal Schottky Diode

Features

- V_R 40V/30V/20V
- I_{FAV} 350mA



Mechanical Data

- **Package:** SOD-323
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end

	Marking
SD103AWS	S4
SD103BWS	S5
SD103CWS	S6

■ Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE	
Reverse voltage	V_R	V	$I_R=100\mu A$	SD103AWS	40
				SD103BWS	30
				SD103CWS	20
Peak forward surge current	I_{FSM}	A	$t_p=8.3ms$, half sine	1.5	
Average forward current	I_{FAV}	mA	$T_c=25^\circ C$	350	
Power dissipation	P_D	mW		200	
Junction temperature	T_j	°C		-55 to +125	
Storage temperature range	T_{stg}	°C		-55 to +150	
Thermal Resistance Junction to Ambient Air	$R_{\theta JA}$	°C /W		500	

■ Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE	
Maximum Forward voltage	V_F	V	$I_F=20mA$, $T_A=25^\circ C$	0.37	
	V_F	V	$I_F=200mA$, $T_A=25^\circ C$	0.60	
Maximum Reverse current	I_R	μA	SD103AWS	$V_R=30V$, $T_A=25^\circ C$	5.0
			SD103BWS	$V_R=20V$, $T_A=25^\circ C$	
			SD103CWS	$V_R=10V$, $T_A=25^\circ C$	
Minimum Breakdown voltage	$V_{(BR)}$	V	$I_R=100\mu A$	SD103AWS	40
				SD103BWS	30
				SD103CWS	20
Typical Junction capacitance	C_J	pF	$V_R=0V$, $f=1MHz$	50	



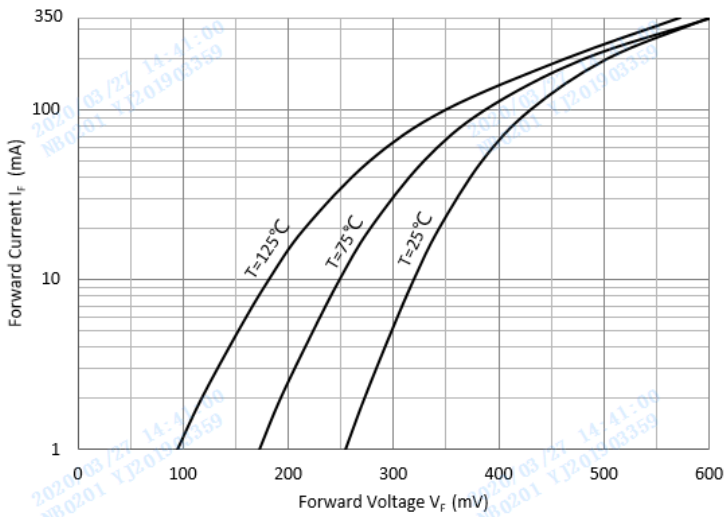
SD103AWS THRU SD103CWS

Ordering Information (Example)

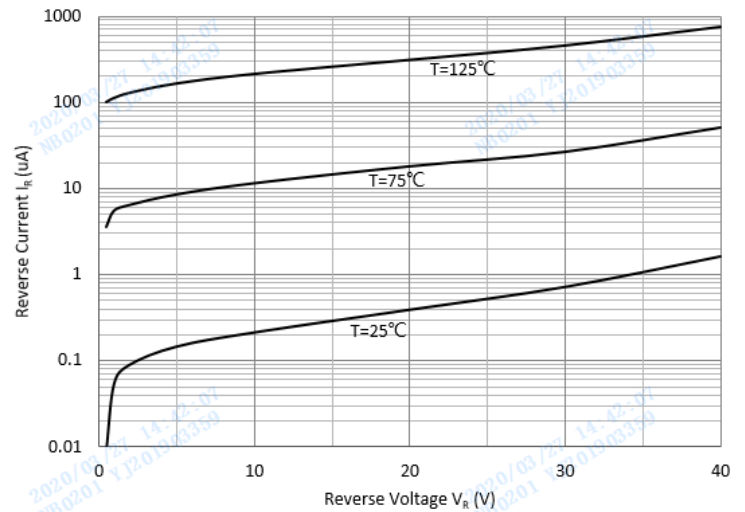
PREFERRED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SD103AWS Thru SD103CWS	F2	Approximate 0.004	3000	30000	120000	7" reel

Characteristics (Typical)

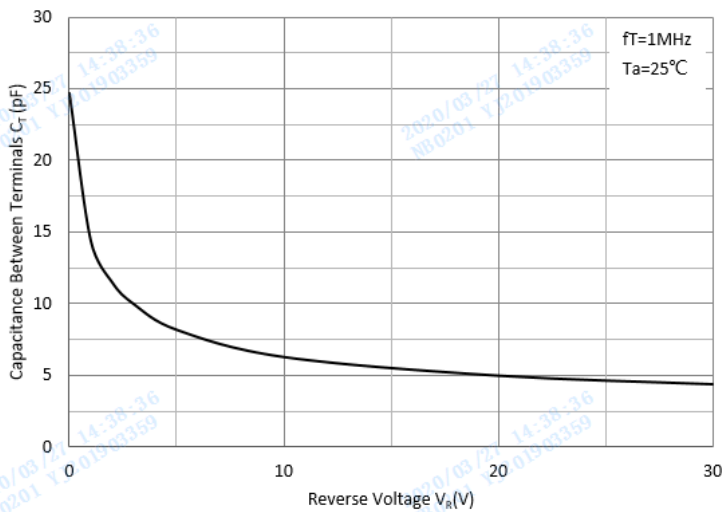
Forward Characteristics



Reverse Characteristics



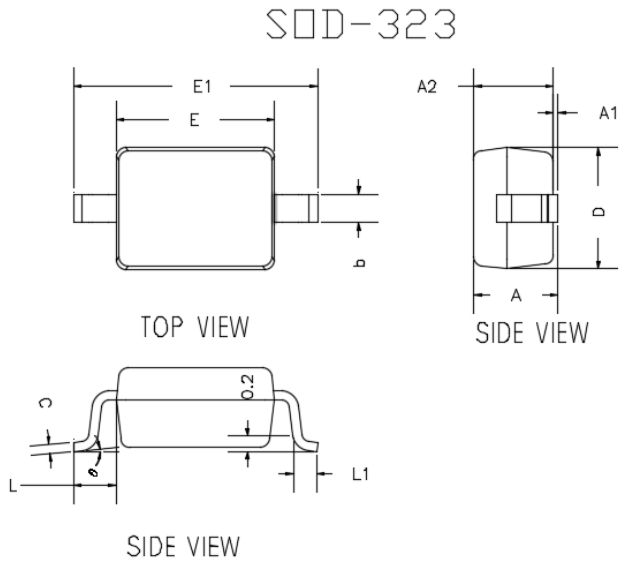
Capacitance Characteristics





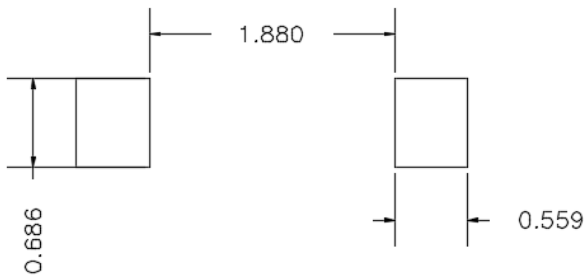
SD103AWS THRU SD103CWS

■ Outline Dimensions



DIMENSIONS				
DIM	INCHES		MM	
	MIN	MAX	MIN	MAX
A	---	0.0393	---	1.0000
A1	0.0000	0.0039	0.0000	0.1000
A2	0.0314	0.0354	0.8000	0.9000
b	0.0098	0.0157	0.2500	0.4000
c	0.0031	0.0059	0.0800	0.1500
D	0.0472	0.0551	1.2000	1.4000
E	0.0629	0.0709	1.6000	1.8000
E1	0.0984	0.1063	2.5000	2.7000
L	0.0187TYP		0.475TYP	
L1	0.0098	0.0157	0.250	0.400
e	0°	8°	0°	8°

■ Soldering Footprint



UNIT : mm

SUGGESTED SOLDER PAD LAYOUT



SD103AWS THRU SD103CWS

Disclaimer

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